

### FEATURES

- ❑ Variable Length 4 or 8-bit Wide Shift Register
- ❑ Selectable Delay Length from 3 to 18 Stages
- ❑ Low Power CMOS Technology
- ❑ Replaces Fairchild TMC2011
- ❑ Load, Shift, and Hold Instructions
- ❑ Separate Data In and Data Out Pins
- ❑ Package Styles Available:
  - 24-pin Plastic DIP
  - 28-pin Plastic LCC, J-Lead

### DESCRIPTION

The **L10C11** is a high-speed, low power CMOS variable length shift register. The L10C11 consists of two 4-bit wide, adjustable length shift registers. These registers share control signals and a common clock. Both shift registers can be programmed together to any length from 3 to 18 stages inclusive, or one register can be fixed at 18 stages of delay while the other is variable. The configuration implemented is determined by the Length Code (L3-0) and the MODE control line as shown in Table 1.

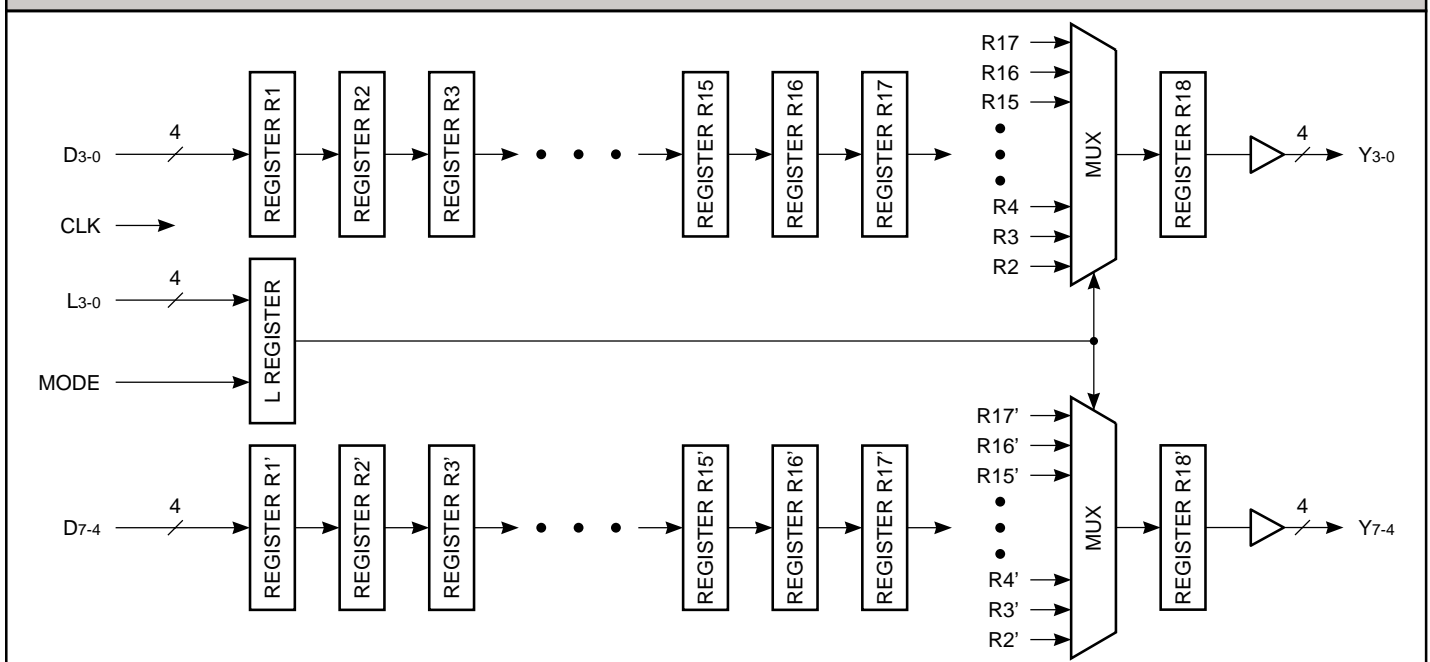
Each input is applied to a chain of registers which are clocked on the rising edge of the common CLK input. These registers are numbered R1 through R17 and R1' through R17', corresponding to the D3-0 and D7-4 data fields respectively. A multiplexer serves to route the contents of any of registers R2 through R17 to the output register, denoted R18. A similar multiplexer operates on the contents of R2' through R17' to load

R18'. Note that the minimum-length path from data inputs to outputs is R1 to R2 to R18, consisting of three stages of delay.

The MODE input determines whether one or both of the internal shift registers have variable length. When MODE = 0, both D3-0 and D7-4 are delayed by an amount which is controlled by L3-0. When MODE = 1, the D7-4 field is delayed by 18 stages independent of L3-0.

The Length Code (L3-0) controls the number of stages of delay applied to the D inputs as shown in Table 1. When the Length Code is 0, the inputs are delayed by 3 clock periods. When the Length Code is 1, the delay is 4 clock periods, and so forth. The Length Code and MODE inputs are latched on the rising edge of CLK. Both the Length Code and MODE values may be changed at any time without affecting the contents of registers R1 through R17 or R1' through R17'.

### L10C11 BLOCK DIAGRAM



**4/8-bit Variable Length Shift Register**

**TABLE 1. CONTROL ENCODING**

Length Code				Mode = 0		Mode = 1	
L3	L2	L1	L0	Delay		Delay	
				Y3-0	Y7-4	Y3-0	Y7-4
0	0	0	0	3	3	3	18
0	0	0	1	4	4	4	18
0	0	1	0	5	5	5	18
0	0	1	1	6	6	6	18
0	1	0	0	7	7	7	18
0	1	0	1	8	8	8	18
0	1	1	0	9	9	9	18
0	1	1	1	10	10	10	18
1	0	0	0	11	11	11	18
1	0	0	1	12	12	12	18
1	0	1	0	13	13	13	18
1	0	1	1	14	14	14	18
1	1	0	0	15	15	15	18
1	1	0	1	16	16	16	18
1	1	1	0	17	17	17	18
1	1	1	1	18	18	18	18

**MAXIMUM RATINGS**  
Above which useful life may be impaired (Notes 1, 2, 3, 8)

Storage temperature .....	-65°C to +150°C
Operating ambient temperature .....	-55°C to +125°C
V <sub>CC</sub> supply voltage with respect to ground .....	-0.5 V to +7.0 V
Input signal with respect to ground .....	-3.0 V to +7.0 V
Signal applied to high impedance output .....	-3.0 V to +7.0 V
Output current into low outputs .....	25 mA
Latchup current .....	> 400 mA

**OPERATING CONDITIONS**  
To meet specified electrical and switching characteristics

Mode	Temperature Range	Supply Voltage
Active Operation, Com.	0°C to +70°C	4.75 V £ V <sub>CC</sub> £ 5.25 V
Active Operation, Mil.	-55°C to +125°C	4.50 V £ V <sub>CC</sub> £ 5.50 V

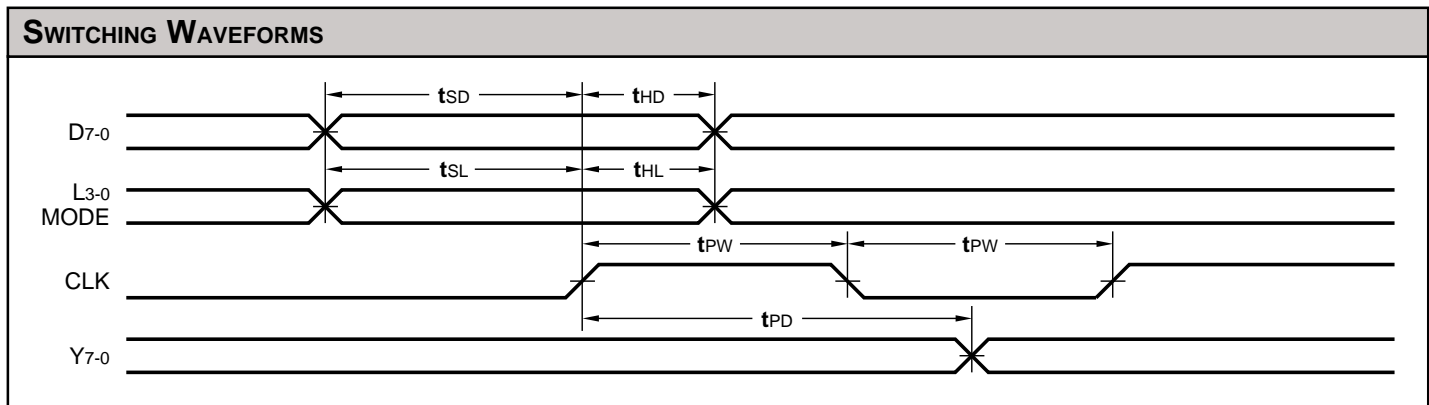
**ELECTRICAL CHARACTERISTICS** Over Operating Conditions (Note 4)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V <sub>OH</sub>	Output High Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = -12 mA	2.4			V
V <sub>OL</sub>	Output Low Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 24 mA			0.5	V
V <sub>IH</sub>	Input High Voltage		2.0		V <sub>CC</sub>	V
V <sub>IL</sub>	Input Low Voltage	(Note 3)	0.0		0.8	V
I <sub>Ix</sub>	Input Current	Ground ≤ V <sub>IN</sub> ≤ V <sub>CC</sub> (Note 12)			±20	µA
I <sub>CC1</sub>	V <sub>CC</sub> Current, Dynamic	(Notes 5, 6)		10	20	mA
I <sub>CC2</sub>	V <sub>CC</sub> Current, Quiescent	(Note 7)			1.0	mA

**SWITCHING CHARACTERISTICS**

<b>COMMERCIAL OPERATING RANGE (0°C to +70°C) Notes 9, 10 (ns)</b>							
Symbol	Parameter	L10C11-					
		25*		20		15	
		Min	Max	Min	Max	Min	Max
t <sub>PD</sub>	Output Delay		25		20		15
t <sub>PW</sub>	Clock Pulse Width	15		12		10	
t <sub>SD</sub>	Data Setup Time	20		10		8	
t <sub>HD</sub>	Data Hold Time	2		0		0	
t <sub>SL</sub>	L3-0, MODE Setup Time	20		10		8	
t <sub>HL</sub>	L3-0, MODE Hold Time	2		0		0	

<b>MILITARY OPERATING RANGE (-55°C to +125°C) Notes 9, 10 (ns)</b>							
Symbol	Parameter	L10C11-					
		30*		25*		20*	
		Min	Max	Min	Max	Min	Max
t <sub>PD</sub>	Output Delay		30		25		20
t <sub>PW</sub>	Clock Pulse Width	15		12		12	
t <sub>SD</sub>	Data Setup Time	25		10		10	
t <sub>HD</sub>	Data Hold Time	2		2		0	
t <sub>SL</sub>	L3-0, MODE Setup Time	25		10		10	
t <sub>HL</sub>	L3-0, MODE Hold Time	2		2		0	



**\*DISCONTINUED SPEED GRADE**

**NOTES**

1. Maximum Ratings indicate stress specifications only. Functional operation of these products at values beyond those indicated in the Operating Conditions table is not implied. Exposure to maximum rating conditions for extended periods may affect reliability.

2. The products described by this specification include internal circuitry designed to protect the chip from damaging substrate injection currents and accumulations of static charge. Nevertheless, conventional precautions should be observed during storage, handling, and use of these circuits in order to avoid exposure to excessive electrical stress values.

3. This device provides hard clamping of transient undershoot and overshoot. Input levels below ground or above VCC will be clamped beginning at -0.6 V and VCC + 0.6 V. The device can withstand indefinite operation with inputs in the range of -0.5 V to +7.0 V. Device operation will not be adversely affected, however, input current levels will be well in excess of 100 mA.

4. Actual test conditions may vary from those designated but operation is guaranteed as specified.

5. Supply current for a given application can be accurately approximated by:

$$\frac{NCV^2F}{4}$$

where

4

- N = total number of device outputs
- C = capacitive load per output
- V = supply voltage
- F = clock frequency

6. Tested with all outputs changing every cycle and no load, at a 5 MHz clock rate.

7. Tested with all inputs within 0.1 V of VCC or Ground, no load.

8. These parameters are guaranteed but not 100% tested.

9. AC specifications are tested with input transition times less than 3 ns, output reference levels of 1.5 V (except tDIS test), and input levels of nominally 0 to 3.0 V. Output loading may be a resistive divider which provides for specified IOH and IOL at an output voltage of VOH min and VOL max respectively. Alternatively, a diode bridge with upper and lower current sources of IOH and IOL respectively, and a balancing voltage of 1.5 V may be used. Parasitic capacitance is 30 pF minimum, and may be distributed.

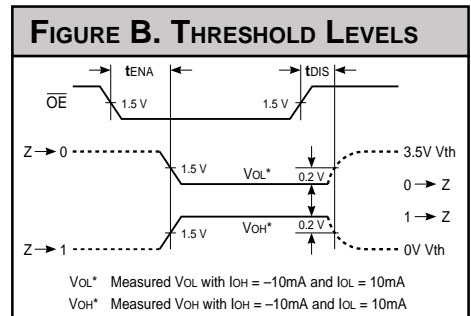
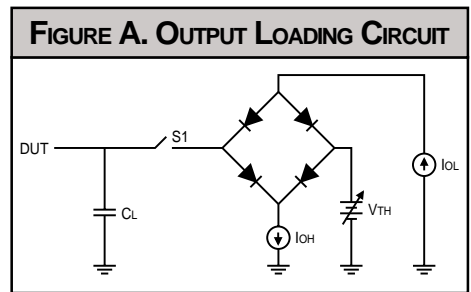
This device has high-speed outputs capable of large instantaneous current pulses and fast turn-on/turn-off times. As a result, care must be exercised in the testing of this device. The following measures are recommended:

- a. A 0.1 μF ceramic capacitor should be installed between VCC and Ground leads as close to the Device Under Test (DUT) as possible. Similar capacitors should be installed between device VCC and the tester common, and device ground and tester common.
- b. Ground and VCC supply planes must be brought directly to the DUT socket or contactor fingers.
- c. Input voltages should be adjusted to compensate for inductive ground and VCC noise to maintain required DUT input levels relative to the DUT ground pin.

10. Each parameter is shown as a minimum or maximum value. Input requirements are specified from the point of view of the external system driving the chip. Setup time, for example, is specified as a minimum since the external system must supply at least that much time to meet the worst-case requirements of all parts. Responses from the internal circuitry are specified from the point of view of the device. Output delay, for example, is specified as a maximum since worst-case operation of any device always provides data within that time.

11. For the tENA test, the transition is measured to the 1.5 V crossing point with datasheet loads. For the tDIS test, the transition is measured to the ±200mV level from the measured steady-state output voltage with ±10mA loads. The balancing voltage, VTH, is set at 3.5 V for Z-to-0 and 0-to-Z tests, and set at 0 V for Z-to-1 and 1-to-Z tests.

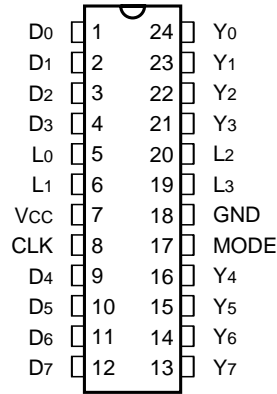
12. These parameters are only tested at the high temperature extreme, which is the worst case for leakage current.



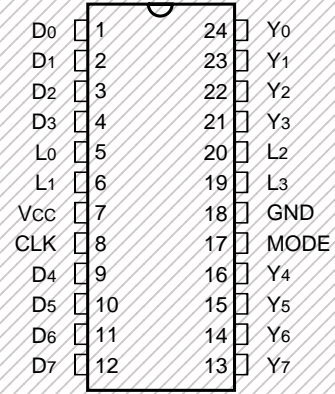
**4/8-bit Variable Length Shift Register**

**ORDERING INFORMATION**

24-pin — 0.3" wide



24-pin — 0.6" wide

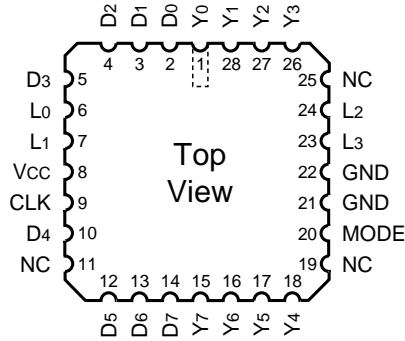


Discontinued Package

Speed	Plastic DIP (P2)		Plastic DIP (P1)
	<b>0°C to +70°C — COMMERCIAL SCREENING</b>		
20 ns 15 ns	L10C11PC20 L10C11PC15		
	<b>-55°C to +125°C — COMMERCIAL SCREENING</b>		
	<b>-55°C to +125°C — MIL-STD-883 COMPLIANT</b>		

**ORDERING INFORMATION**

28-pin



<b>Speed</b>	<b>Plastic J-Lead Chip Carrier (J4)</b>		
<b>0°C to +70°C — COMMERCIAL SCREENING</b>			
20 ns 15 ns	L10C11JC20 L10C11JC15		
<b>-55°C to +125°C — COMMERCIAL SCREENING</b>			
<b>-55°C to +125°C — MIL-STD-883 COMPLIANT</b>			